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Claim Amendments:

Please amend the claims as indicated:

Claims 1-18 (Withdrawn)

19. (Currently Amended) An electronic package A multi-chip module, comprising:
a first semiconductor device capable of enabling functionality associated with a first
circuit segment of an integrated circuit design and ~~including an array including a~~
~~set of first device interconnect pads;~~
a second semiconductor device capable of enabling functionality associated with a
second circuit segment of the integrated circuit design and ~~including an~~
~~array including a set of second device interconnect pads; and~~
a plurality of device interconnect members, each one of said device interconnect
members being electrically connected directly between one of said first device
interconnect pads and a corresponding one of said second device interconnect
pads.

20. (Currently Amended) The electronic package multi-chip module of claim 19
wherein:

the first semiconductor device ~~includes~~ is capable of enabling functionality associated
with a first functional block of the integrated circuit design; and
the second semiconductor device ~~device~~ is capable of enabling functionality associated
with a second functional block of the integrated circuit design.

21. (Currently Amended) The electronic package multi-chip module of claim 19
wherein:

the first semiconductor device is a DRAM device; and
the second semiconductor device is a logic device.

22. (Currently Amended) The electronic package multi-chip module of claim 19
wherein:

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the first semiconductor device is made from a first type of semiconductor substrate; and the second semiconductor device is made from a second type of semiconductor substrate.

23. (Currently Amended) The electronic package~~multi-chip module~~ of claim 19 wherein each one of said device interconnect members is a solder-type interconnect member.

24. (Currently Amended) The electronic package~~multi-chip module~~ of claim 23 wherein the solder-type interconnect member is a solder bump.

25. (Currently Amended) The electronic package~~multi-chip module~~ of claim 23 wherein the solder-type interconnect member is a solder ball.

26. (Currently Amended) The electronic package of claim 19 wherein the electronic package is a multichip module and the plurality of device interconnect members includes solder-type interconnect members. A multi-chip module comprising:

a first semiconductor device capable of enabling functionality associated with a first functional block of an integrated circuit design and including an array of first device interconnect members;

a second semiconductor device capable of enabling functionality associated with a second functional block of the integrated circuit design and including an array of second device interconnect members; and

a plurality of solder-type interconnect members, each one of said solder-type interconnect members being electrically connected directly between one of said first device interconnect members and a corresponding one of said second device interconnect members.

27. (Currently Amended) The electronic package~~multi-chip module~~ of claim 26 wherein:

the first semiconductor device is a DRAM device; and
the second semiconductor device is a logic device.

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28. (Currently Amended) The electronic package~~multi-chip module~~ of claim 26 wherein:

the first semiconductor device is made from a first type of semiconductor substrate; and
the second semiconductor device is made from a second type of semiconductor substrate.

29. (Currently Amended) The electronic package~~multi-chip module~~ of claim 26 wherein the solder-type interconnect member is a solder bump.

30. (Currently Amended) The electronic package~~multi-chip module~~ of claim 26 wherein the solder-type interconnect member is a solder ball.

31. (Currently Amended) An electronic package, The electronic package of claim 19, further comprising:

an interposer circuit including a dielectric substrate and an array of routing elements attached to the dielectric substrate; and

~~a first semiconductor device capable of enabling functionality associated with a first circuit segment of an integrated circuit design and including an array of first device interconnect pads;~~

~~a second the second semiconductor device capable of enabling functionality associated with a second circuit segment of the integrated circuit design, including an array of second device interconnect pads and including~~ further comprising a set of package-level interconnect pads; and

~~a plurality of device interconnect members, each one of said device interconnect members being electrically connected directly between one of the said first device interconnect pads and a corresponding one of said second device interconnect pads; and~~

a plurality of package-level interconnect members, each one of said package-level interconnect members being electrically connected between one of the said package-level interconnect pads of the second semiconductor device and a corresponding one of said routing elements of the interposer circuit.

32. (Original) The electronic package of claim 31 wherein:

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the first semiconductor device includes is capable of enabling functionality associated with a first functional block of the integrated circuit design; and
the second semiconductor device is capable of enabling functionality associated with a second functional block of the integrated circuit design.

33. (Original) The electronic package of claim 31 wherein:
the first semiconductor device is a DRAM device; and
the second semiconductor device is a logic device.

34. (Original) The electronic package of claim 31 wherein:
the first semiconductor device is made from a first type of semiconductor substrate; and
the second semiconductor device is made from a second type of semiconductor substrate.

35. (Original) The electronic package of claim 31 wherein each one of said device interconnect members is a solder-type interconnect member.

36. (Original) The electronic package of claim 35 wherein the solder-type interconnect member is a solder bump.

37. (Original) The electronic package of claim 35 wherein the solder-type interconnect member is a solderball.

38. (Original) The electronic package of claim 31 wherein:
the interposer circuit is a flip-chip interposer circuit; and
each one of said package-level interconnect members is a solder-type interconnect member.

39. (Original) The electronic package of claim 31 wherein:
the interposer circuit is a wire-bond interposer circuit; and
each one of said package-level interconnect members is a conductive wire.

40. (Cancelled)

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41. (Currently Amended) The electronic package of claim 35~~claim 40~~ wherein:
the first semiconductor device is a DRAM device; and
the second semiconductor device is a logic device.

42. (Currently Amended) The electronic package of claim 35~~claim 40~~ wherein:
the first semiconductor device is made from a first type of semiconductor substrate; and
the second semiconductor device is made from a second type of semiconductor substrate.

43. (Currently Amended) The electronic package of claim 35~~claim 40~~ wherein the
solder-type interconnect member is a solder bump.

44. (Currently Amended) The electronic package of claim 40~~claim 35~~ wherein the
solder-type interconnect member is a solder ball.

45. (Currently Amended) The electronic package of claim 40~~claim 35~~ wherein:
the interposer circuit is a flip-chip interposer circuit; and
each one of said package-level interconnect members is a solder-type interconnect
member.

46. (Currently Amended) The electronic package of claim 40~~claim 35~~ wherein:
the interposer circuit is a wire-bond interposer circuit; and
each one of said package-level interconnect members is a conductive wire.